APPENDIX B. Basic Elements

Basic Element	Basic Element Step(s)
100	NO FINISH REQUIRED.
103	DETAIL OF BONDED ASSEMBLY, DO NOT FINISH.
104	DETAIL OF WELDED ASSEMBLY, DO NOT FINISH.
105	CLEAN PER FPS-3001, PARA. 3.1.1 AND CHEMICAL FILM ALL SURFACES PER MIL-C-5541.
106	CLEAN PER FPS-3001, PARA. 3.1.1 AND BRUSH CHEMICAL FILM PER MIL-C-5541, EXTERIOR SURFACES OF BONDED ASSEMBLY. AS AN ALTERNATE, CHEM FILM MAY BE APPLIED TO EXTERIOR SURFACES OF BONDED ASSEMBLY BY DIPPING WITH THE FOLLOWING RESTRICTIONS: 1. LEAK TEST SHALL HAVE BEEN PERFORMED. 2. NO ELEVATED TEMPERATURE CLEANING OR DRYING OF THE BONDED ASSEMBLY SHALL BE EMPLOYED PRIOR TO THE DIPPING OPERATION.
107	CLEAN PER FPS-3001, PARA. 3.1.1 AND CHEMICAL FILM PER MIL-C-5541 EXTERIOR SURFACES ONLY. TREATMENT IS OPTIONAL ON INSIDE DIAMETER.
108	CLEAN PER FPS-3001, PARA. 3.1.1 AND CHEMICAL FILM PER MIL-C-5541 EXTERIOR SURFACES ONLY. TREATMENT NOT PERMITTED ON INSIDE DIAMETER.
109	CLEAN PER FPS-3001 AFTER FINAL ASSEMBLY.
111	CLEAN AND ANODIZE PER FPS-3033 OR FPS-3090 OR CLEAN PER FPS-3001 PARA. 3.1.1 AND ANODIZE ALL SURFACES PER MIL-A-8625, TYPE I. 1. IF ELECTRICAL BONDING IS REQUIRED ON SPECIFIED AREAS BY REFERENCE TO FPS-3024, ANODIZE ONLY THOSE SURFACES NOT SPECIFIED FOR ELECTRICAL BONDING PER 114. PREPARE SURFACES SPECIFIED FOR ELECTRICAL BONDING PER MIL-C-5541 CLASS 3. 2. AFTER ANODIZE, INSPECT ANODIZED SURFACE FOR DARKENED AREAS OF DISCOLORATION WHICH MAY INDICATE SOFT MATERIAL. PARTS CONTAINING SUCH SPOTS SHALL MEET THE REQUIREMENTS OF NDTS 1500 PRIOR TO ANODIZE COATING ACCEPTANCE.
112	CLEAN PER FPS-3001, PARA. 3.1.1 AND SULFURIC ACID ANODIZE ALL SURFACES PER MIL-A-8625, CLASS 1, TYPE II, DUPLEX SEALED
113	CLEAN PER FPS-3001, PARA 3.1.1 AND HARD ANODIZE ALL SURFACES PER MIL-A-8625, TYPE III, UNSEALED. 1. IF ELECTRICAL BONDING IS REQUIRED ON SPECIFIED AREAS BY REFERENCE TO FPS-3024, HARD ANODIZE PER 113 ONLY THOSE SURFACES NOT SPECIFIED FOR ELECTRICAL BONDING. PREPARE SURFACES SPECIFIED FOR ELECTRICAL BONDING PER MIL-C-5541 CLASS 3.